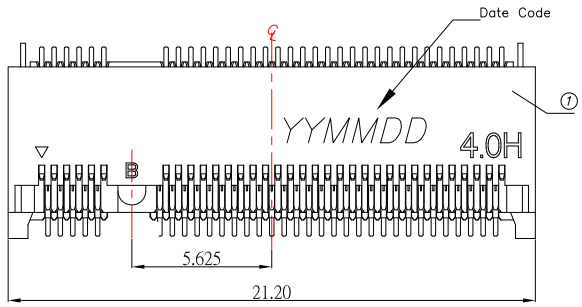
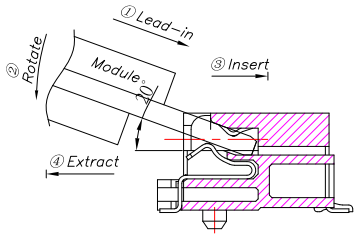
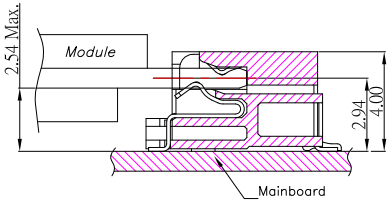
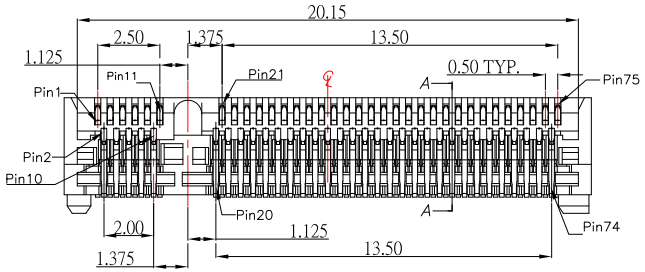
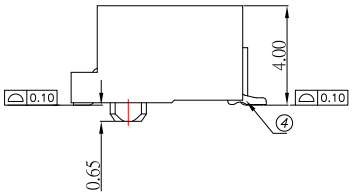


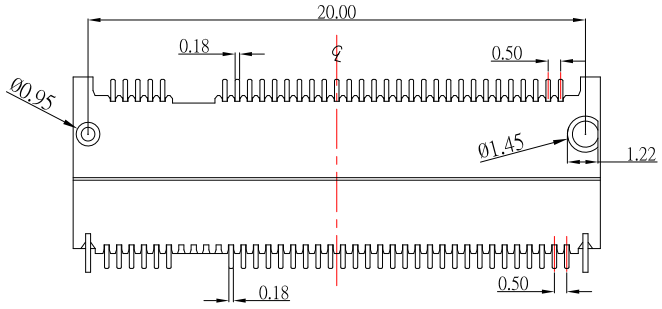


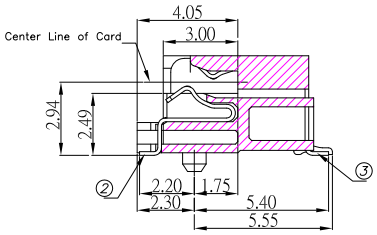
How to mate and unmate
Mate: ① – ② – ③
Unmate: ④











SECTION A–A

NGF-40S1B-xx-S273

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"

COLOR :

Black: B
White : W

1.SPECIFICATION:

1.1 Current Rate: 0.5 A

1.2 Voltaget Rate: 50V AC

1.3 Insulator Resistance: 500 MΩ Min

1.4 Dielectric Strength: 300V AC

1.5 Contact Resistance: 20mΩ Max

1.6 Mating Force: 20N Max

1.7 Unmating Force: 20N Max

2.MATERIAL:

2.1 Housing: LCP,UL94V-0

2.2 Contact: Phosphor Bronze

2.3 Leg: Brass

3.Finish:

3.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

3.2 Leg: Tin Plated on Solder Balls
Nickel under plated overall

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新料號及MODLE	Jack	050416

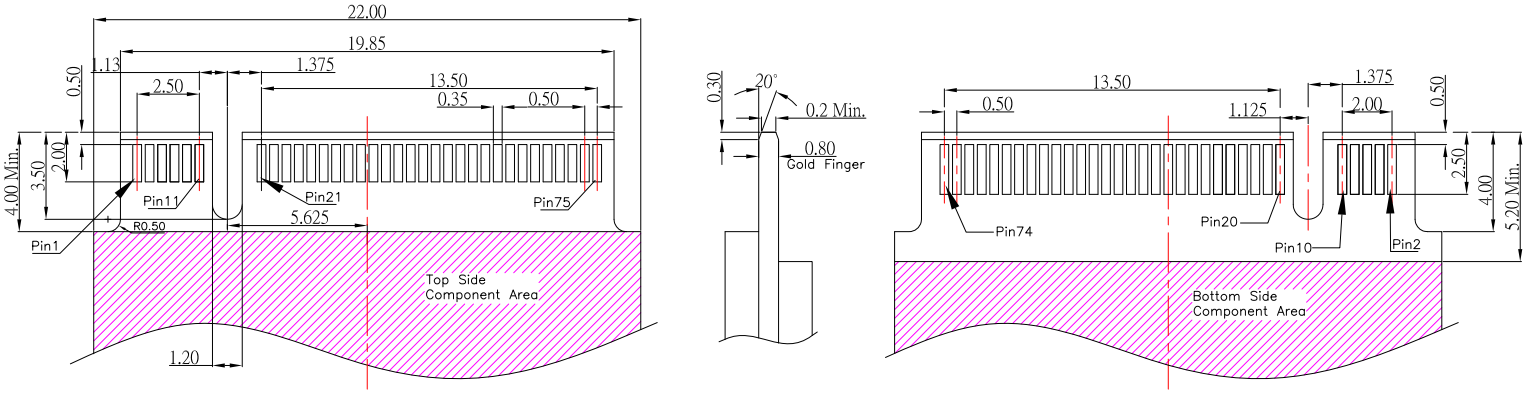
CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

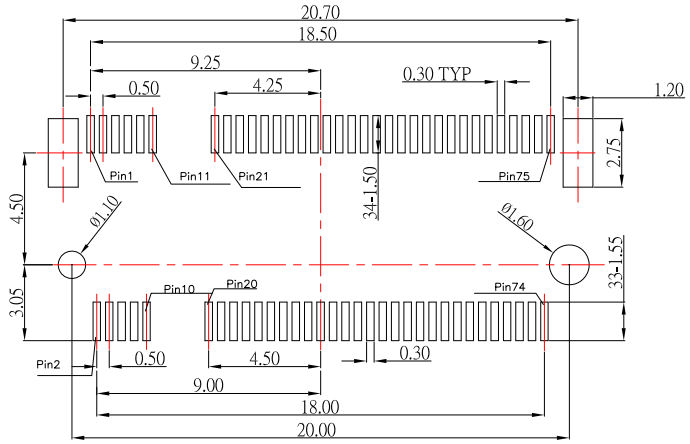
3RD. ANGEL'S | UNITS MM

		DATE
DRAWN BY:	Jack Lu	05/04/16
CHECKED BY:	Jacky Chen	05/04/16
APPROVED BY:	Tony Kao	05/04/16

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	NGFF SOCKET 板上4.0H 正向 B KEY
SCALE	1 : 1	DWG NO.	NGF-40S1B-xx-S273 SIZE A4
SHEET NO.	1 of 2	PART NO.	NGF-40S1B-xx-S273 VER R1



Recommended Mould Finger Layout



Recommended PCB Layout(Top View)

1	更新料號及MODLE	Jack	050416
ITEM NO.	DESCRIPTION	DRAWN	DATE

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS MM

DRAWN BY: Jack Lu	DATE 05/04/16	MAT'L	
CHECKED BY: Jacky Chen	DATE 05/04/16	FINISH	
APPROVED BY: Tony Kao	DATE 05/04/16	SCALE 1 : 1	SHEET NO. 2 of 2

TITLE	CONNECTOR		
MODLE	NGFF SOCKET 板上4.0H 正向 B KEY		
DWG NO.	NGF-40S1B-xx-S273	SIZE	A4
PART NO.	NGF-40S1B-xx-S273	VER	R1